

# NanoFrazor – A Nanolithography Tool for 2D & 3D Devices

**Nils Goedecke**

Tero Kulmala, ZhenMing Wu, Felix Holzner

Heidelberg Instruments Nano, Technoparkstrasse 1, Zurich, Switzerland

[Nils.goedecke@himt.ch](mailto:Nils.goedecke@himt.ch), [www.heidelberg-instruments.com](http://www.heidelberg-instruments.com)

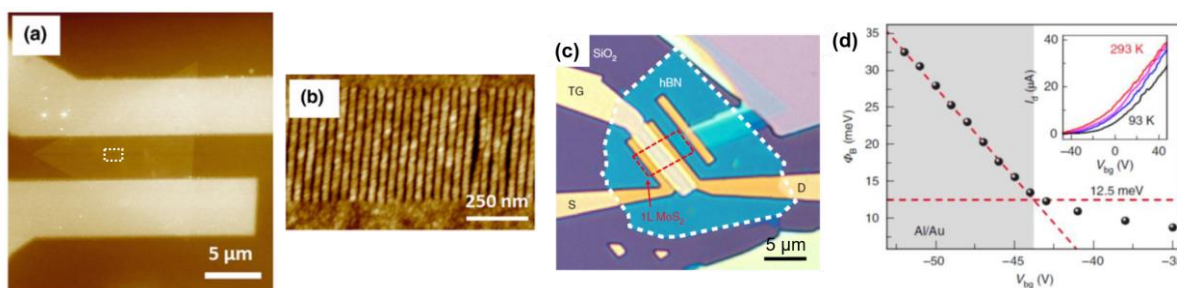
NanoFrazor (thermal scanning probe) lithography has recently entered the market as the first true alternative to electron beam lithography (EBL) [1]. Core of the technology is a heatable probe tip that is used for both patterning and simultaneous inspection of complex nanostructures. The heated tip can pattern very high-resolution (< 10 nm half-pitch) nanostructures by locally evaporating resist materials. The structures are inspected by the cold tip in parallel with the patterning process, enabling stitching and markerless overlay with sub-5 nm accuracy [2]. The technique is compatible with all the common pattern transfer processes [3,4,5].

Shaping 2D materials into narrow ribbons, Hall bars etc. is often required in order to study their properties. Another challenge is formation of high-quality electrical contacts on them. Predominant fabrication process - i.e. EBL followed by etching or lift-off of metal – has its resolution limited by proximity effects, may require complex overlay procedures and typically yields poor quality non-ohmic metal contacts with high Schottky barriers and large contact resistances [6]. Here, we show that NanoFrazor lithography can be used for shaping 2D materials with very high precision (Figure 1a-b) [7] and for forming high-quality metal contact electrodes on them (Figures 1 c–d) [5]. The fabricated devices exhibit vanishing Schottky barrier heights (around 0 meV, Figure 1d), record-high on/off ratios of 10<sup>10</sup>, no hysteresis, and subthreshold swings as low as 64 mV per decade.

## References

- [1] Garcia et al., *Nature Nanotechnology* 9, 577 (2014).
- [2] Rawlings et al., *ACS Nano* 9, 6188 (2015).
- [3] Wolf et al., *J. Vac. Sci. Technol. B* 33, 02B102 (2015).
- [4] Kulmala et al., *Proc. SPIE* 1058412 (2018).
- [5] Zheng et al., *Nature Electronics* 2 17-25 (2019).
- [6] Allain et al., *Nature Materials* 14, 1195–1205 (2015).
- [7] Ryu and Knoll, *Electrical Atomic Force Microscopy for Nanoelectronics*, 143-172 (Ed. U. Celano), Springer Nature Switzerland AG (2019).

## Figures



**Figure 1:** a) AFM image of 18-nm half-pitch 1L MoS<sub>2</sub> nanoribbon array patterned along the zigzag direction. (b) A close-up of the region marked with a white dashed box in (a). Figures (a) and (b) from Ref [7]. (c) Optical image of a 1L MoS<sub>2</sub> FET with a h-BN gate dielectric where the source, drain and top-gate electrodes have been patterned with a NanoFrazor. (d) Gate voltage dependence of Schottky barrier height of a 1L MoS<sub>2</sub> FET with Al/Au contacts ( $V_{ds} = 2$  V). The deviation from the linear response at low  $V_{bg}$  (dashed red line) defines the flat band voltage and the SBH. Inset, corresponding temperature-dependent transfer curves ( $V_{ds} = 2$  V). Figures (c) and (d) from Ref. [5].